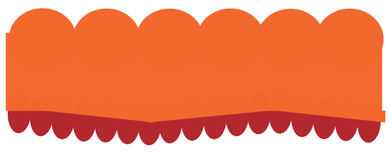
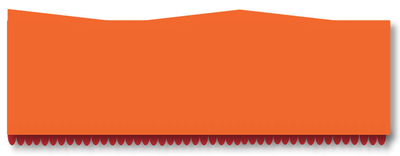
高速伝送用電解銅箔

ED copper foil series for high speed data transmission

三井金属

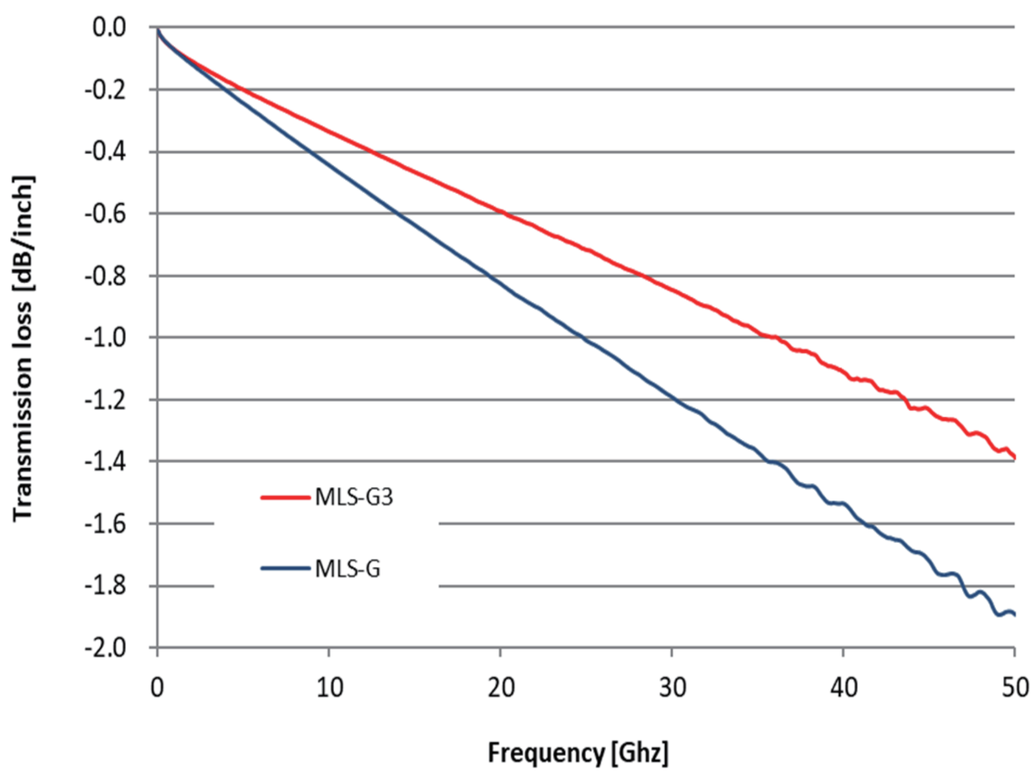
製品名：MLS™-G / MLS™-G3 / MLS™-G4 / HS1-VSP™ / HS2-VSP™ / SI-VSP™ / SI2-VSP™

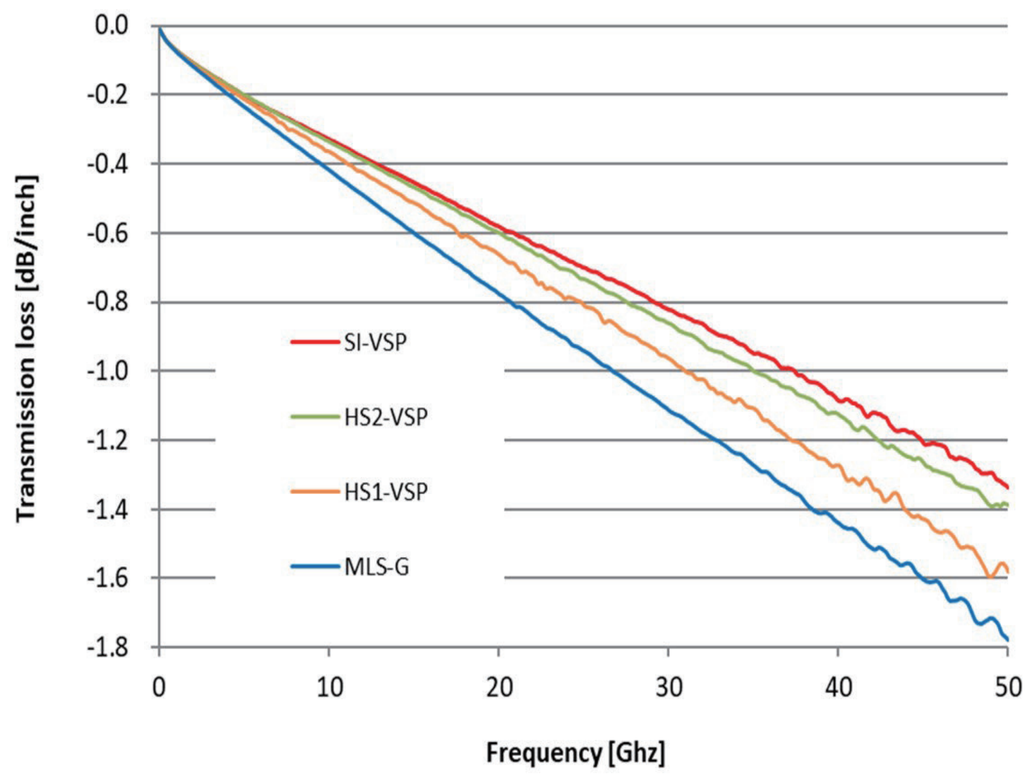
- VSP密着面側の超低粗度化により伝送損失を大幅に低減
- Model No: HS1-VSP™ / HS2-VSP™ / SI-VSP™ copper foils with very low profile.
- Combined with low Dk/Df materials to show very low signal loss.
- 表面処理技術によりLow Dk/Df樹脂との良好な密着強度及び耐熱特性を実現
- Good bonding characteristics with low Dk/Df materials.

Model No.	Cross Section Image	Roughness B-side Rz	Thickness	Status
MLS™-G		3.5μm	1/2oz 1oz 2oz	Mass Production
MLS™-G3 MLS™-G4		1.5μm		
HS1-VSP™ HS2-VSP™		1.5μm 1.0μm		
SI-VSP™ SI2-VSP™		0.6μm 0.5μm		

■ 伝送損失比較 Signal Loss at high frequency (SI data)

Dielectric : Low loss Prepreg 136um, Dk 3.08, Df 0.0027
Cu thickness : 18μm Impedance : 50Ω
Measurement mode : Microstrip Line / Single





記載内容は予告なく変更する場合があります。2024年6月11日現在

Copyright © Mitsui Mining & Smelting Co., Ltd. All Rights Reserved.